EVERY CONNECTION COUNTS

WHEN TECHNOLOGY CONNECTS, SO DOES HUMANITY.
OUR PURPOSE

WE CREATE A SAFER, SUSTAINABLE, PRODUCTIVE AND CONNECTED FUTURE.
INDUSTRIAL TECHNOLOGY LEADERSHIP

15K+
PATENTS
granted or pending

$675M+
INVESTED in engineering,
research & development

8000+
ENGINEERS
globally

Approximately
20%
of sales from
new products

All figures from FY21

Top 100 Global
Innovator
2022

Fortune
World's Most Admired Companies 2022

Approximately

INDUSTRIAL TECHNOLOGY

leadership

FORTUNE

THE WORLD'S
MOST ADMIRED
COMPANIES
2022

Clarivate
With Great Power Comes Great Sustainability

GREENHOUSE GAS INTENSITY
FY20 VS FY10

ENERGY USE INTENSITY
FY20 VS FY10

WATER USAGE
FY20 VS FY10

$5.6M
GLOBAL CHARITABLE GIVING FY20

650K+
PEOPLE IMPACTED IN NEXT-GENERATION TECHNOLOGY EDUCATION FY20

$2.1B
LOCAL ECONOMIC IMPACT FROM SUPPLY CHAIN FY20

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EVERY CONNECTION COUNTS

TE Connectivity (TE) Data and Devices
Focused Portfolio for a Dynamic Market
## Solutions for IoT End Points and the Edge

### Wire-to-Board
TE offers an extremely broad array of products to address wire-to-board requirements.

### Input / Output (I/O)
From RJ45 to USB connectors, TE can deliver I/O solutions for reliable connectivity with the rest of the business network.

### Power
From distribution of power to internal and external power interconnects, TE can keep your power flowing.

### Card & Socket Connectors
From IC sockets to SD cards, TE can make it easy to get connected and process, share or store data.

### Board-to-Board
TE’s free height surface-mount connectors address today’s industry requirements for high density packaging.

### Connectors
TE has high-density, small centerline spacing solutions, plus related contacts and accessories.

### Spring Fingers
TE’s miniaturized solutions help reduce and control the effect of EMI in most complex systems.

### Embedded Antennas
Standard and custom high-performance antennas can address most wireless protocols.

### Micro Coax
TE offers off-the-shelf printed circuit board (PCB) receptacles and mating cable assemblies, as well as custom micro coax cable assemblies.

### External Antennas
The newly acquired Laird Connectivity External Antennas business brings with it a long history of associated quality and customer service with their external antenna product portfolio.
Industries & Solutions

INNOVATIVE CONNECTIVITY SOLUTIONS THAT HELP CUSTOMERS DELIVER PERFORMANCE BEYOND DATA CENTER AND IOT END DEVICES

AEROSPACE & DEFENSE
AUTOMATION & CONTROL
POWER DISTRIBUTION
SAFETY & SECURITY
MATERIAL HANDLING
TEST & MEASUREMENT
LIGHTING
AUTO INFOTAINMENT
HVAC
INTELLIGENT BUILDINGS
### Connectivity Solutions Beyond Data Center and IoT End Devices

<table>
<thead>
<tr>
<th>Category</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Building Safety &amp; Security</strong></td>
<td>Achieve real-time, mobile monitoring capability across multiple locations and facilities</td>
</tr>
<tr>
<td><strong>Industrial Controls</strong></td>
<td>Focus on production equipment utilization and uptime with integrated diagnostic capabilities</td>
</tr>
<tr>
<td><strong>Lighting</strong></td>
<td>Meet the demand for increased energy efficiency and provide dimming and color control</td>
</tr>
<tr>
<td><strong>Industrial Power Distribution</strong></td>
<td>Drive for smarter power and increased efficiency in most harsh conditions</td>
</tr>
<tr>
<td><strong>Auto Infotainment</strong></td>
<td>Focus on high-quality consumer port applications, board-to-board connections, wireless, and vehicle-to-vehicle communication</td>
</tr>
<tr>
<td><strong>Instrumentation &amp; Measurement</strong></td>
<td>Speed and accuracy of data collection for research, development, test and evaluation</td>
</tr>
<tr>
<td><strong>Elevators &amp; Escalators</strong></td>
<td>Improved safety and capacity management</td>
</tr>
<tr>
<td><strong>HVAC – Cooling &amp; Rotary</strong></td>
<td>Expectation of cloud-based systems to help drive Ethernet and wireless connectivity at the equipment level</td>
</tr>
<tr>
<td><strong>Material Handling</strong></td>
<td>Conservation of both space and power, while sharing large amounts of information</td>
</tr>
<tr>
<td><strong>Aerospace, Defense &amp; Marine</strong></td>
<td>Faster data to address the most stringent quality and performance standards</td>
</tr>
</tbody>
</table>
Data and Devices Product Portfolio

- Cable & Cable Assemblies
- Power
- Input / Output
- Board-to-Board
- RF, Antennas & Shielding
- Internal and Sockets
**TE is Leading Innovation**

<table>
<thead>
<tr>
<th>Busbar Connectors</th>
<th>Busbar Assembly</th>
</tr>
</thead>
<tbody>
<tr>
<td><img src="image1" alt="Busbar Connectors Images" /></td>
<td><img src="image2" alt="Busbar Assembly Images" /></td>
</tr>
</tbody>
</table>

- **Solutions for power delivery in server, switch, wireless, industrial control and modular power supplies.** Commonly used in rack-mounted equipment with busbar architecture
- **Benefits:** Reliable, low resistance, robust
- **Applications:** IT tray, cubby shelf, battery backup unit (BBU) and power shelf

- **Solutions for 12V and 48V+ requirements**
- **Benefits:** Reliable and robust power delivery
- **Offerings:** Board mount, flexible braided wire, pin and socket and cables available for versatility and customization
- **Applications:** rack busbar, shelf power, switch, EV charging and controls
TE is Leading Innovation

**Sliver Interconnects for SFF-TA-1002**

- The Sliver connector design was incorporated into the new industry standard SFF-TAA-1002 specification which was adopted in reference applications by OCP, EDSFF and Gen-Z.
- Chosen for performance, density, flexibility and robustness
- Offerings: mid-board connectors, card edge connectors and cable assemblies

**Thermal Bridge**

- TE’s innovative thermal bridge technology can provide up to 2x better thermal resistance over traditional thermal technologies used in liquid cooling, cold plate or restricted airflow applications.
- Better reliability and durability
- Improved application serviceability
- Offerings: small form-factor pluggable plus (SFP+), quad small form-factor pluggable double density (QSFP-DD) and quad small form-factor pluggable 28 (QSFP28) plus customized solutions for other I/O form factors
TE is Leading Innovation

**112G per lane I/O Solutions**

- We are at the forefront of developing 112G per lane solutions for 800G and lower aggregate port bandwidths. Our products deliver high performance and meet specifications set by multi-source agreements (MSA) groups.

- Thermal management is becoming challenging across most high speed I/O connectors. TE has a wide portfolio of cage designs and mounts to fit various forced air and liquid cooling architectures dissipating 25W+ powers.

- Offerings: octal small form-factor pluggable (OSFP), quad small form-factor pluggable (QSFP), QSFP double density (QSFP-DD), small form-factor pluggable (SFP), SFP double density (SFP-DD), CDFP

**Over the board (OTB) Solutions**

- Cabled solutions adoption between I/O panel mount connectors have been increasing to counter lossy PCB traces and costly retimers. TE is developing these cabled solutions for most lead I/O form factors.

- Offerings: Up to 16DP and 32DP low profile near-ASIC connectors which can provide flexibility and performance.

- Key value proposition: High DP near-ASIC, low profile to fit under most heat sink applications, 112G per lane capability, flexibility to help connect single or ganged connectors...many more
## TE is Leading Innovation

<table>
<thead>
<tr>
<th>LGA 4189 Sockets</th>
<th>Customized Sockets</th>
</tr>
</thead>
<tbody>
<tr>
<td><img src="image1.png" alt="LGA 4189 Sockets" /></td>
<td><img src="image2.png" alt="Customized Sockets" /></td>
</tr>
</tbody>
</table>

- LGA 4189 sockets support Intel next-generation central processing units (CPUs) for higher performance and better system scaling.
- LGA 4189 sockets are designed for Intel’s next-generation processors, which can support PCIe Gen 4 and four or eight-multi-processor system architectures.
- Innovative, customized socket and hardware solutions for computing, networking and AI purpose ICs.
- A large one-piece socket up to 10K pin count and 112 Gbps speed.
## Leading the Way in Compute & Networking Solutions

<table>
<thead>
<tr>
<th>Sliver Internal Cabled Interconnects</th>
<th>Mini-SAS HD Connectors and Cable Assemblies</th>
<th>Cabled STRADA Whisper Backplane Connectors</th>
</tr>
</thead>
<tbody>
<tr>
<td><img src="image1.jpg" alt="Image" /></td>
<td><img src="image2.jpg" alt="Image" /></td>
<td><img src="image3.jpg" alt="Image" /></td>
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</tbody>
</table>
| • Slim interface supports wide variety of protocols  
  • Rated up to 112G PAM4 and 56G NRZ  
  • Sliver interconnect products comply with SFF-TA-1002 specification | • Industry-proven solution to address SFF-8086, 8087, and 8088 standards  
  • Supports SAS 2.0, SAS 2.1, SAS 3 and PCIe applications  
  • Rated up to 6 Gbps and 12 Gbps | • Flexible solution to help run longer channels  
  • Support 112G PAM4 and 56G NRZ  
  • Excellent EMI performance  
  • Cable receptacle also available |

TE is a leader in innovative connectivity solutions for high-speed computing and networking applications. Our products can provide the speed and connection dependability needed to efficiently handle ever-increasing amounts of data.
Our active optical cable assembly portfolio provides improved cable flexibility and longer reach as compared to both traditional passive copper and emerging active copper (ACC/AEC) solutions, supporting high performance computing, data center and networking interconnect applications.
Features and Benefits

Comprehensive Product Range
• 28G NRZ, 56G and 112G PAM-4 per channel
• SFP, QSFP and QSFP-DD form factors in both straight and breakout configurations

Ease of Installation
• Offers longer reach and lighter weight interconnects compared to copper cables
• Smaller bend radius than copper alternatives

Reduced Power and Latency
• Lower power consumption and lower latency for 56G PAM-4 using analog CDR as compared to DSP (25% power reduction, 100x latency improvement)

Product Versatility
• Meets MSA operating requirements within the end-customers applications
• Digital Diagnostics Monitoring (DDM) Interface allows customer management and monitoring of key modules parameters
• Cables available in custom lengths as required
Applications

- High-speed interconnects within and between switches, routers and transport equipment
- High Performance Computing
- Server-Server Clusters (AI/ML)
- Interconnects rack-to-rack, shelf-to-shelf, board-to-board, board-to-optical backplane
- InfiniBand applications
28G NRZ Active Optical Cables (AOC)

28G SFP28 AOC

- Multi-rate capability: 10 Gbps to 25.78125 Gbps, full-duplex
- Single 3.3 V power supply
- Low power consumption: < 1 W
- Up to 70m (OM3) / 100m (OM4)
- Built-in digital diagnostic functions (SFF-8472)
- Hot pluggable
- RoHS compliant
- Commercial operating case temperature range: 0 to 70°C

<table>
<thead>
<tr>
<th>Product</th>
<th>Part number</th>
<th>Length (m)</th>
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<tbody>
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<tr>
<td>SFP28-SFP28, AOC</td>
<td>2418078-8</td>
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</tr>
</tbody>
</table>

100G QSFP28 AOC

- Multi-rate capability: 10 Gbps to 25.78125 Gbps per channel, 4-channel full-duplex
- Single 3.3 V power supply
- Low power consumption: ≤ 2.5 W per cable end
- Up to 70m (OM3) / 100m (OM4)
- Built-in digital diagnostic functions (SFF-8636)
- Hot pluggable
- RoHS compliant
- Commercial operating case temperature range: 0 to 70°C

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<td>QSFP28-QSFP28, AOC</td>
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</tbody>
</table>
100G QSFP28 to SFP28 AOC

- Multi-rate capability: 10 Gbps to 25.78125 Gbps, 4 independent full-duplex
- Single 3.3 V power supply
- Low power consumption: ≤ 2.5W on QSFP end, < 1 W on SFP end
- Up to 70m (OM3) / 100m (OM4)
- Built-in digital diagnostic functions (SFF-8636 and SFF-8472)
- Hot pluggable
- RoHS compliant
- Commercial operating case temperature range: 0 to 70°C

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<tr>
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</table>

56G PAM-4 Active Optical Cables (AOC)

56G SFP56 AOC

- Up to 53.125 Gbps data rate per channel by PAM 4 modulation, full-duplex
- Single 3.3 V power supply
- Low power consumption: 2W
- Up to 70m (OM3)
- Built-in digital diagnostic functions (SFF-8472)
- Hot pluggable
- Commercial operating case temperature range: 0 to 70°C

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</tbody>
</table>
200G QSFP56 AOC

- Up to 53.125 Gbps data rate per channel by PAM 4 modulation, 4-channel full-duplex
- Single 3.3 V power supply
- Low power consumption: < 4 W per cable end
- Up to 70m (OM3) / 100m (OM4)
- Built-in digital diagnostic functions (CMIS rev 4.0)
- Hot pluggable
- RoHS compliant
- Commercial operating case temperature range: 0 to 70°C

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</table>

400G QSFP-DD AOC

- Up to 53.125 Gbps data rate per channel by PAM 4 modulation
- Single 3.3 V power supply
- Low power consumption: < 8 W per cable end
- Up to 70m (OM3) / 100m (OM4)
- Built-in digital diagnostic functions (CMIS rev 4.0)
- Hot pluggable
- RoHS compliant
- Commercial operating case temperature range: 0 to 70°C

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</tbody>
</table>
400G QSFP-DD to 2x QSFP56 AOC

- Up to 53.125 Gbps data rate per channel by PAM 4 modulation
- Single 3.3 V power supply
- Low power consumption: < 8 W on QSFP-DD end, < 4 W on QSFP56 end
- Up to 70m (OM3) / 100m (OM4)
- Built-in digital diagnostic functions (CMIS rev 4.0)
- Hot pluggable
- RoHS compliant
- Commercial operating case temperature range: 0 to 70°C

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</table>
As the Internet of Things (IoT) expands and the growing connected world generates exponentially more data, efficient and reliable storage solutions become even more critical within the data center. Whether you are designing to scale up or scale out with your data center storage solutions, TE connectivity (TE) has a broad range of input/output (I/O), board-to-board, power products and more to help you achieve your storage performance objectives. We combine innovation and quality, dependable products with the flexibility to deliver storage interconnect solutions practically anywhere in the world. We are your partner for creating the solutions that meet the demand of the next generation of our data-driven world.

FIND OUT MORE

te.com/storagesolutions
# DATA AND DEVICES // DATA CENTER STORAGE

## INPUT/OUTPUT (I/O)

Maximize your density & speed with our pluggable I/O products which support standard interfaces.

- **QSFP**
  - OSFP integrates thermal management directly into the form factor, eliminating the high thermal resistance between the module and the heat sink.
  - QSFP-DD doubles the density of QSFP and eight differential pairs capable of 50 Gbps each to achieve 400Gbe while allowing existing QSFP modules to be plunged into the same cage.
- **SFP/SFP+/zSFP+**
  - SFP interconnects support data rates up to 56 Gbps. Many cage configurations offer excellent shielding options.
  - QSFP/QSFP+/zQSFP+ The quad small form factor pluggable (QSFP) portfolio of interconnects offers a large range of simple and customizable design options up to 56 Gbps.
- **Mini-SAS HD Connectors**
  - Designed to provide next-generation speeds for both internal and external applications.

## MEMORY & SOCKETS

We have a range of solderless, compression-mount sockets and the latest in memory connectors.

- **DDR4 DIMM**
  - Space savings, reduced height, improved power consumption, and higher data rates than the DDR3.
- **Land Grid Array (LGA) Sockets**
  - Socket technology for microprocessor packages up to 10,000+ positions.
- **SATA Connectors**
  - Alignment-free and slant insertion styles provide solutions for PCB space saving.
- **SAS Connectors**
  - These mainstream storage solutions are designed to support differential signaling at speeds of up to 12 Gbps.
- **Mini PCI Express and mSATA**
  - Right angle, surface mount expansion card sockets for express mini cards or display mini cards.

## HIGH SPEED BACKPLANE

The right backplane solution provides high-speed and critical scalability for growing data demand.

- **STRADA Whisper Connectors**
  - Transfer data at speeds of 56 Gbps with scalability up to 112 Gbps—upgrade without costly backplane redesigns.
- **Impact Connectors**
  - This system is available in two designs providing flexibility to optimize for advanced mechanical and electrical performance.
- **Z-PACK Slim UHD High-Speed Connectors**
  - Designed to be among the densest connectors with the smallest possible footprint to free up valuable PCB space.
- **Z-PACK TinMan Connectors**
  - A proven performer now with reduced impedance.

## POWER

Robust and reliable bus bar, cable, hot-pluggable and blind mating solutions for storage applications.

- **MULTI-BEAM XLE Connectors**
  - Space saving pluggable series with slim guide sockets and vented housing allows better heat dissipation.
- **ELCON Mini Power Connectors**
  - Low profile solutions with up to 40A per contact and positive latch retention for cable-to-PCB applications.
- **RAPID LOCK Connectors**
  - No install tools required; fast, reliable replacement for power lugs.
- **Power Bus Bar Cable Assemblies**
  - Provides efficient and reliable power distribution and quick installation in a plug-and-play design.
- **CROWN CLIP Senior**
  - Offers a low insertion/extraction force for high-current mating directly to a power bus bar.
- **CROWN CLIP Junior**
  - Space efficient hot pluggable design for power supply and distribution applications.

## INTERNAL INTERCONNECTS

Our latest high-speed, high-density connectors support a variety of storage designs.

- **Sliver Interconnects**
  - Flexible, robust & provides optimal signal integrity, while also saving space and lowering design costs.
- **M.2 NGFF Connectors**
  - Save more than 20% of PCB real estate compared to the PCI Express Mini Card.
- **Free Height Connectors**
  - These versatile connectors are useful for downsizing applications that require parallel stacked circuit boards.
- **STRADA Mesa Connectors**
  - These mezzanine connectors have a pin and socket signal design and offer integrated power contacts.

## COPPER CABLE ASSEMBLIES

Supporting the latest standards for 56 Gbps and beyond. Custom solutions available.

- **SFP**
  - Features 12G, high-density, high-speed interface designed to save 30% to 50% PCB space.
- **Mini-SAS HD**
  - Features 12G, high-density, high-speed interface designed to save 30 to 50.
- **QSFP/SFP**
  - With 8 differential pairs, these assemblies provide 4 channels at speeds up to 56 Gbps per channel.

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**te.com/storagesolutions**

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*5G ready solutions may vary within a product family. Please refer to te.com or contact your TE sales representative for additional information.

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[5G solutions are helping to unlock the potential of 5G. Our portfolio of 5G solutions and capabilities address key challenges faced by design engineers around the world.*]
TE Connectivity’s (TE) global experience in a wide range of connectivity applications helps our customers “design in” efficiency and agility into data center infrastructure and data center equipment. We have a full set of interconnect and cabling solutions to increase bandwidth, density and reliability for all types of telecommunications and enterprise routing and switching equipment.

We offer products for applications at 10, 25, 40, 100 and up to 400 Gbps to support converged internet protocol (IP) networks. Count on us to provide solutions to support your enterprise’s current and future demand for data, speed, and power efficiency.
## DATA CENTER SWITCHING AND ROUTERS

### INPUT/OUTPUT (I/O)
- **Maximize your density & speed with our pluggable I/O products which support standard interfaces.**
  - **QSFP**
    - QSFP integrates thermal management directly into the form factor, eliminating the high thermal resistance between the module and the heat sink.
  - **QSFP-DD**
    - QSFP-DD doubles the density of QSFP and eight differential pairs capable of 50 Gbps each to achieve 400GbE while allowing existing QSFP modules to be plugged into the same cage.
  - **SFP/SFP+/zSFP+**
    - SFP interconnects support data rates up to 56 Gbps. Many cage configurations offered provide excellent shielding options.
  - **QSFP/QSFP+/zQSFP+**
    - The quad small form factor pluggable (QSFP) portfolio of interconnects offers a large range of simple and customizable design options up to 56 Gbps.
- **Mini-SAS HD Connectors**
  - Designed to provide next-generation speeds for both internal and external applications.
- **ETHERNET**
  - TE’s modular jacks and plugs offer reliable and space saving solutions for flexible, time-saving installation, even in harsh environments.
- **RS45 Connectors**
  - Extensive portfolio with many configurations and solutions up to a Cat6 performance rating.
- **RJ point five Connectors**
  - This next-gen Ethernet link offers higher density solutions for a competitive total cost of ownership per port.

### HIGH SPEED BACKPLANE
- **Provide high-speed and scalability for core, edge, Ethernet, and other applications across switches and routers.**
  - **STRADA Whisper Connectors**
    - Transfer data at speeds of 56 Gbps with a roadmap to 112 Gbps—upgrade without costly backplane redesigns.
  - **Impact Connectors**
    - This system is available in two designs providing flexibility to optimize for advanced mechanical and electrical performance.
  - **Z-PACK Slim UHD High-Speed Connectors**
    - Designed to be among the densest connectors with the smallest possible footprint to free up valuable PCB space.
  - **Z-PACK HM-Zd Plus Connectors**
    - Reduce noise and system crosstalk with this double-ground design.
  - **DDR4 DIMM Connectors**
    - Space savings, reduced height, improved power consumption, and higher data rates than the DDR3.

### INTERNAL INTERCONNECTS
- **Our latest high-speed, high-density interconnects support a range of switching and router designs.**
  - **Free Height Connectors**
    - These versatile connectors are useful for downsizing applications that require parallel stacked circuit boards.
  - **Fine Pitch Board-to-Board (BTB)**
    - 0.4 mm pitch plus new shielded board-to-FPC solution.
  - **Mini CT Connectors**
    - Miniature wire-to-board connectors that feature a compact pitch design.
  - **DDR4 DIMM Connectors**
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### POWER
- **Robust and reliable busbar, cable, hot-pluggable and blind mating solutions.**
  - **MULTI-BEAM XLE Connectors**
    - This hot pluggable series is a space guide sockets and vented housing for better heat dissipation.
  - **CROWN CLIP Senior**
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  - **CROWN CLIP Junior**
    - Space efficient hot pluggable design for power supply and distribution applications.
  - **Power Bus Bar Cable Assemblies**
    - Provides efficient and reliable power distribution and quick installation in a plug-and-play design.
  - **MINIPAK HDL**
    - High density, blind-mateable power interface for board-to-board connections. Stand only 8mm off the edge of the PCB and the contacts are rated at 16A.
  - **Universal Power Module**
    - Modular power connectors that are compliant with many backplane signal connector designs. They are hot pluggable and a high reliability solution.

### COPPER CABLE ASSEMBLIES
- **Supporting the latest standards for 56 Gbps and beyond. Custom solutions available.**
  - **ELCON Mini Power Connectors**
    - Low profile solutions with up to 40A per contact and positive latch retention for cable-to-PCB applications.
  - **Bus Bar Connectors**
    - Available in board-to-bus bar, wire-to-bus bar and board-to-board configurations. Provides a separable connection, easy assembly, inspection and troubleshooting.
  - **Bus Bar Assembly**
    - Power solution that requires less space, provides better heat dissipation and easier installation when compared to cable assemblies.

**NOTE:**
- These solutions are helping to unlock the potential of 5G. Our portfolio of 5G solutions and capabilities address key challenges faced by design engineers around the world.
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DATA CENTER SERVERS

Servers are the heart of the data network. TE Connectivity (TE) offers the solutions you need to keep your servers running. Our backplane, board-to-board, I/O, power and copper cable solutions help enable server architectures that address industry needs of higher bandwidth and improved thermal management. We offer a complete portfolio of complementary products and agile system expertise to help you optimize the design of your server configuration whether blade, rack mount or sleds. In addition to solutions for disaggregated systems, we can extend your reach, reduce your power consumption, and increase speed and density to address the demands of always-connected data centers.

FIND OUT MORE
tecomm/serversolutions
## DATA AND DEVICES // DATA CENTER SERVERS

### HIGH SPEED BACKPLANE

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<td>QSFP28 Copper Cables</td>
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<td>QSFP+ 32AWG Cables</td>
<td>Fine wire cable that’s ultra-thin, light weight &amp; highly flexible for high density intra-rack applications.</td>
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### POWER

- **From bus bar to cable, hot-pluggability and blind mating—solutions for almost any server configuration.**
- **SATA**
  - Alignment-free and slant insertion styles provide solutions for PCB space saving.
- **DDR4 DIMM Connectors**
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- **Bus Bar Connectors**
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- **Bus Bar Assembly**
  - Power solution that requires less space, provides better heat dissipation and easier installation when compared to cable assemblies.
- **Sliding Power Connector**
  - Allows hot swapping of components in a server drawer and is excellent for applications up to 75A. Eliminates the need for bulky cable management systems.
ANY CONNECTION CAN CHANGE THE WORLD